

Electronic Patent Application Fee Transmittal

Application Number:	10632568
Filing Date:	02-Aug-2003
Title of Invention:	SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING PACKAGE STACKED OVER BALL GRID ARRAY PACKAGE AND HAVING WIRE BOND INTERCONNECT BETWEEN STACKED PACKAGES
First Named Inventor/Applicant Name:	Marcos Karnezos
Filer:	Bill Kennedy/Paula Hurley
Attorney Docket Number:	CPAC 1017-3

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700